

24-Stage Frequency Divider

MC14521B

The MC14521B consists of a chain of 24 flip-flops with an input circuit that allows three modes of operation. The input will function as a crystal oscillator, an RC oscillator, or as an input buffer for an external oscillator. Each flip-flop divides the frequency of the previous flip-flop by two, consequently this part will count up to $2^{24} = 16,777,216$. The count advances on the negative going edge of the clock. The outputs of the last seven-stages are available for added flexibility.

Features

- All Stages are Resettable
- Reset Disables the RC Oscillator for Low Standby Power Drain
- RC and Crystal Oscillator Outputs Are Capable of Driving External Loads
- Test Mode to Reduce Test Time
- V_{DD}' and V_{SS}' Pins Brought Out on Crystal Oscillator Inverter to Allow the Connection of External Resistors for Low-Power Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

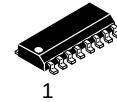
Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in} , V_{out}	-0.5 to V_{DD} +0.5	V
Input or Output Current (DC or Transient) per Pin	I_{in} , I_{out}	± 10	mA
Power Dissipation, per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	-55 to +125	°C
Storage Temperature Range	T_{stg}	-65 to +150	°C
Lead Temperature (8-Second Soldering)	T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. Operating the device outside its recommended conditions, but still within its maximum rated limits may not cause immediate damage. However, doing so can lead to reduced performance, unpredictable behavior, and potentially shorten the device's lifespan or reliability.

1. Temperature Derating: "D/DW" Package: -7.0 mW/°C From 65 °C To 125 °C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

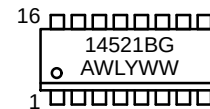


SOIC-16
D SUFFIX
CASE 751B

PIN ASSIGNMENT

Q24	1	16	V_{DD}
RESET	2	15	Q23
V_{SS4}	3	14	Q22
OUT 2	4	13	Q21
V_{DD4}	5	12	Q20
IN 2	6	11	Q19
OUT1	7	10	Q18
V_{SS}	8	9	IN 1

MARKING DIAGRAMS



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

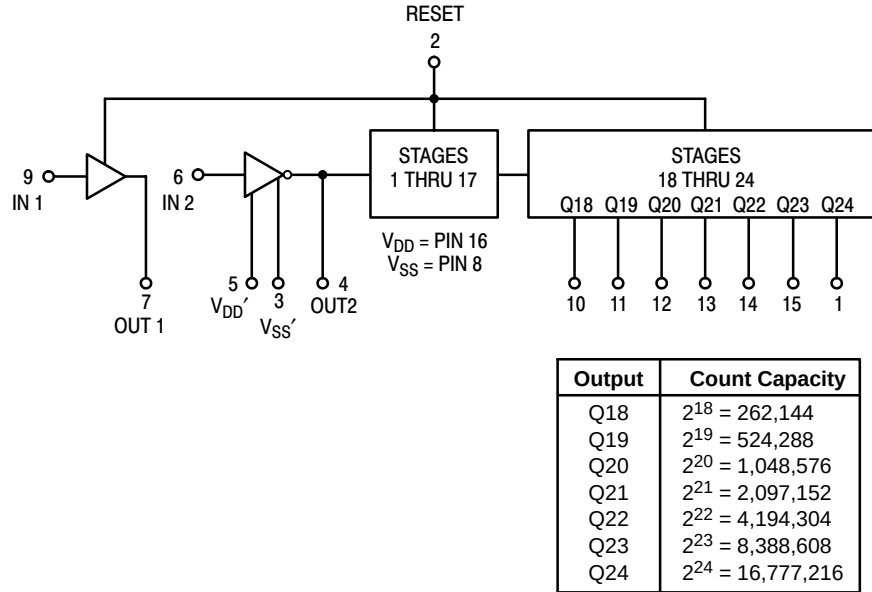
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 2.

MC14521B

BLOCK DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14521BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14521BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NLV14521BDR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

DISCONTINUED (Note 2)

NLV14521BDG*	SOIC-16 (Pb-Free)	48 Units / Rail
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[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

* NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

2. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on www.onsemi.com.



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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	–55 °C		25 °C			125 °C		Unit		
			Min	Max	Min	Typ (Note 3)	Max	Min	Max			
Output Voltage “0” Level V _{in} = V _{DD} or 0	V _{OL}	5.0 10 15	– – –	0.05 0.05 0.05	– – –	0 0 0	0.05 0.05 0.05	– – –	0.05 0.05 0.05	Vdc		
“1” Level V _{in} = 0 or V _{DD}	V _{OH}	5.0 10 15	4.95 9.95 14.95	– – –	4.95 9.95 14.95	5.0 10 15	– – –	4.95 9.95 14.95	– – –	Vdc		
Input Voltage “0” Level (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	5.0 10 15	– – –	1.5 3.0 4.0	– – –	2.25 4.50 6.75	1.5 3.0 4.0	– – –	1.5 3.0 4.0	Vdc		
“1” Level (V _O = 0.5 or 4.5 Vdc) (V _O = 1.0 or 9.0 Vdc) (V _O = 1.5 or 13.5 Vdc)	V _{IH}	5.0 10 15	3.5 7.0 11	– – –	3.5 7.0 11	2.75 5.50 8.25	– – –	3.5 7.0 11	– – –	Vdc		
Output Drive Current (V _{OH} = 4.5 Vdc) (V _{OH} = 9.0 Vdc) (V _{OH} = 13 Vdc)	I _{OH} Source Pin 4	5.0 10 15	–0.25 –0.62 –1.8	– – –	–0.2 –0.5 –1.5	–0.36 –0.9 –3.5	– – –	–0.14 –0.35 –1.1	– – –	mAdc		
(V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)		Source Pins 1, 7, 10, 11, 12, 13, 14 and 15	5.0 5.0 10 15	–3.0 –0.64 –1.6 –4.2	– – – –	–2.4 –0.51 –1.3 –3.4	–4.2 –0.88 –2.25 –8.8	– – – –	–1.7 –0.36 –0.9 –2.4	– – – –	mAdc	
(V _{OL} = 0.4 Vdc) (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)			Sink	5.0 10 15	0.64 1.6 4.2	– – –	0.51 1.3 3.4	0.88 2.25 8.8	– – –	0.36 0.9 2.4	– – –	mAdc
Input Current				I _{in}	15	–	±0.1	–	±0.00001	±0.1	–	±1.0
Input Capacitance (V _{in} = 0)	C _{in}	–		–	–	–	5.0	7.5	–	–	pF	
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	– – –	5.0 10 20	– – –	0.005 0.010 0.015	5.0 10 20	– – –	150 300 600	μAdc		
Total Supply Current (Note 4, 5) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15	I _T = (0.42 μA/kHz) f + I _{DD} I _T = (0.85 μA/kHz) f + I _{DD} I _T = (1.40 μA/kHz) f + I _{DD}							μAdc		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

4. The formulas given are for the typical characteristics only at 25 °C.

5. To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + (C_L – 50) Vfk where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.003.



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SWITCHING CHARACTERISTICS (Note 6) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 7)	Max	Unit
Output Rise and Fall Time (Counter Outputs) $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 12.5 \text{ ns}$	t_{TLH}, t_{THL}	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q18 $t_{PHL}, t_{PLH} = (1.7 \text{ ns/pF}) C_L + 4415 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.66 \text{ ns/pF}) C_L + 1667 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.5 \text{ ns/pF}) C_L + 1275 \text{ ns}$ Clock to Q24 $t_{PHL}, t_{PLH} = (1.7 \text{ ns/pF}) C_L + 5915 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.66 \text{ ns/pF}) C_L + 2167 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.5 \text{ ns/pF}) C_L + 1675 \text{ ns}$	t_{PHL}, t_{PLH}	5.0 10 15 5.0 10 15	– – – – – –	4.5 1.7 1.3 6.0 2.2 1.7	9.0 3.5 2.7 12 4.5 3.5	μs
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 1215 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 467 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 350 \text{ ns}$	t_{PHL}	5.0 10 15	– – –	1300 500 375	2600 1000 750	ns
Clock Pulse Width	$t_{WH(cl)}$	5.0 10 15	385 150 120	140 55 40	– – –	ns
Clock Pulse Frequency	f_{cl}	5.0 10 15	– – –	3.5 9.0 12	2.0 5.0 6.5	MHz
Clock Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	– – –	– – –	15 5.0 4.0	μs
Reset Pulse Width	$t_{WH(R)}$	5.0 10 15	1400 600 450	700 300 225	– – –	ns
Reset Removal Time	t_{rem}	5.0 10 15	30 0 –40	–200 –160 –110	– – –	ns

6. The formulas given are for the typical characteristics only at 25°C .

7. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

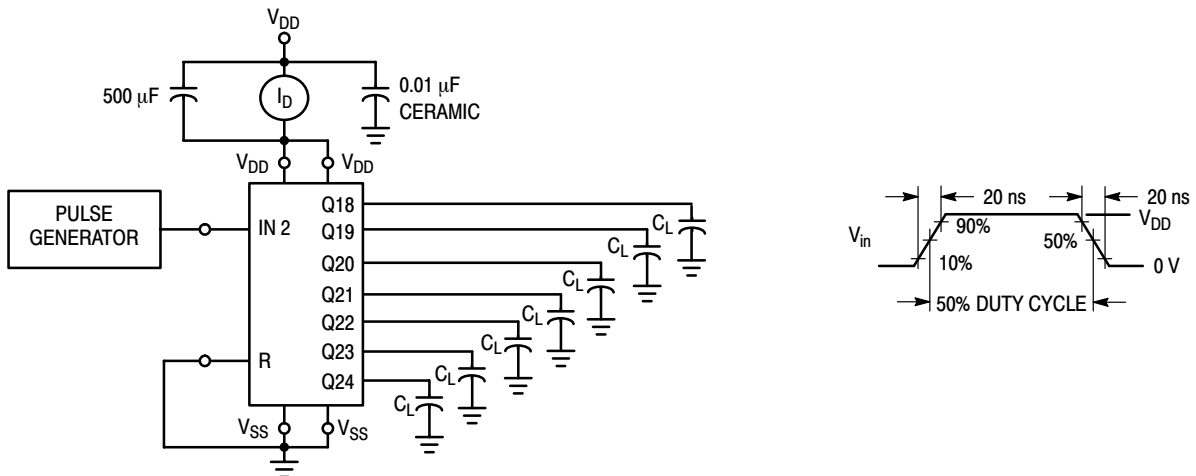


Figure 1. Power Dissipation Test Circuit and Waveform

MC14521B

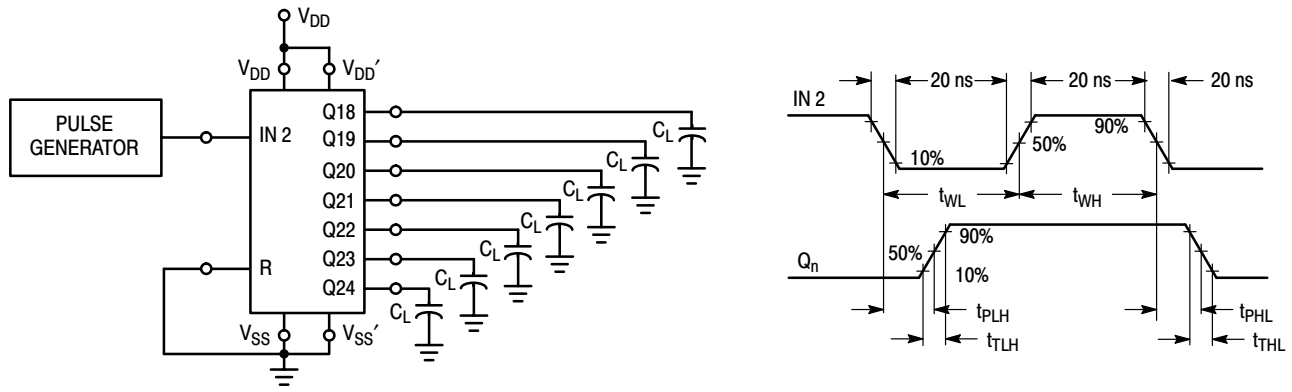
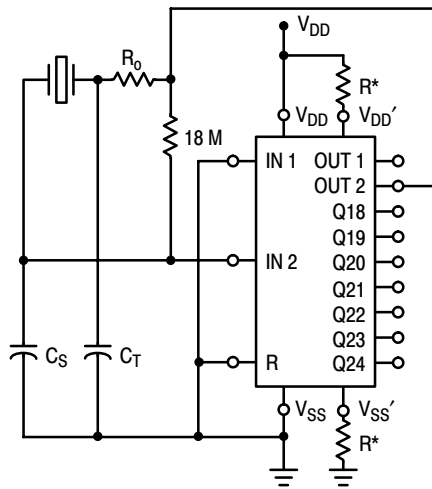


Figure 2. Switching Time Test Circuit and Waveforms



* Optional for low power operation,
10 kΩ ≤ R ≤ 70 kΩ.

Figure 3. Crystal Oscillator Circuit

Characteristic	500 kHz Circuit	50 kHz Circuit	Unit
Crystal Characteristics			
Resonant Frequency	500	50	kHz
Equivalent Resistance, R_S	1.0	6.2	kΩ
External Resistor/Capacitor Values			
R_o	47	750	kΩ
C_T	82	82	pF
C_S	20	20	pF
Frequency Stability			
Frequency Change as a Function of V_{DD} ($T_A = 25^\circ\text{C}$)			
V_{DD} Change from 5.0 V to 10 V	+ 6.0	+ 2.0	ppm
V_{DD} Change from 10 V to 15 V	+ 2.0	+ 2.0	ppm
Frequency Change as a Function of Temperature ($V_{DD} = 10\text{ V}$)			
T_A Change from -55°C to $+25^\circ\text{C}$	- 4.0	- 2.0	ppm
MC14521 only	+ 100	+ 120	ppm
Complete Oscillator*			
T_A Change from $+25^\circ\text{C}$ to $+125^\circ\text{C}$	- 2.0	- 2.0	ppm
MC14521 only	- 160	- 560	ppm
Complete Oscillator*			

*Complete oscillator includes crystal, capacitors, and resistors.

Figure 4. Typical Data for Crystal Oscillator Circuit

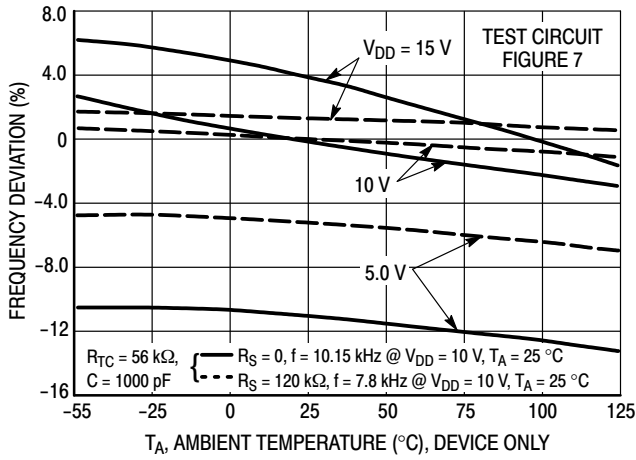


Figure 5. RC Oscillator Stability

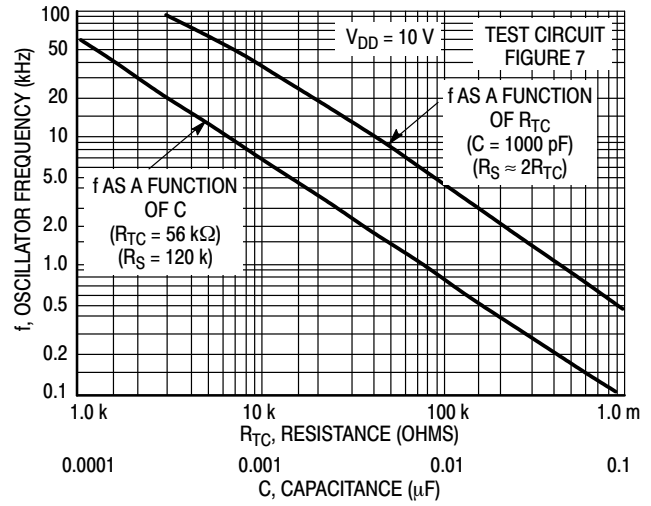


Figure 6. RC Oscillator Frequency as a Function of R_{TC} and C

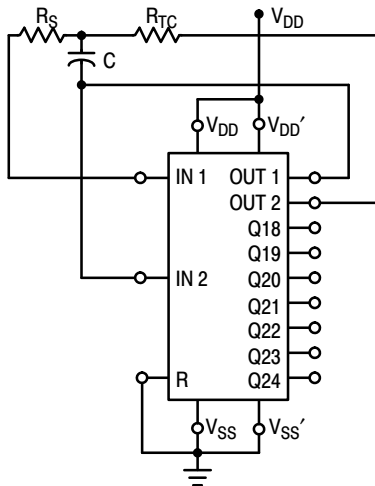


Figure 7. RC Oscillator Circuit

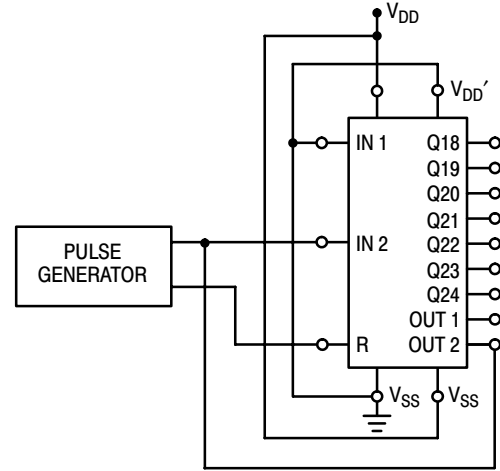


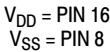
Figure 8. Functional Test Circuit

FUNCTIONAL TEST SEQUENCE

	Inputs		Outputs				Comments
	Reset	In 2	Out 2	V _{SS} '	V _{DD} '	Q18 thru Q24	
A test function (see Figure 8) has been included for the reduction of test time required to exercise all 24 counter stages. This test function divides the counter into three 8-stage sections, and 255 counts are loaded in each of the 8-stage sections in parallel. All flip-flops are now at a logic "1". The counter is now returned to the normal 24-stages in series configuration. One more pulse is entered into Input 2 (In 2) which will cause the counter to ripple from an all "1" state to an all "0" state.	1	0	0	V _{DD}	GND	0	Counter is in three 8-stage sections in parallel mode Counter is reset. In 2 and Out 2 are connected together.
	0	1	1	↓	↓	0	First "0" to "1" transition on In 2, Out 2 node.
		0	0				255 "0" to "1" transitions are clocked into this In 2, Out 2 node.
		1	1				
		–	–				
		–	–	↓	↓	1	The 255th "0" to "1" transition.
		1	1				
		0	0				Counter converted back to 24-stages in series mode.
		0	0				
		1	0	↓	↓	1	Counter converted back to 24-stages in series mode.
		1	0				Out 2 converts back to an output.
		0	1				Counter ripples from an all "1" state to an all "0" stage.



LOGIC DIAGRAM



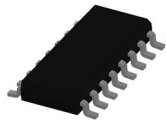
MC14521B

REVISION HISTORY

Revision	Description of Changes	Date
11	Rebranded the Data Sheet to onsemi format. NLV14521BDG OPN marked as Discontinued.	10/3/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

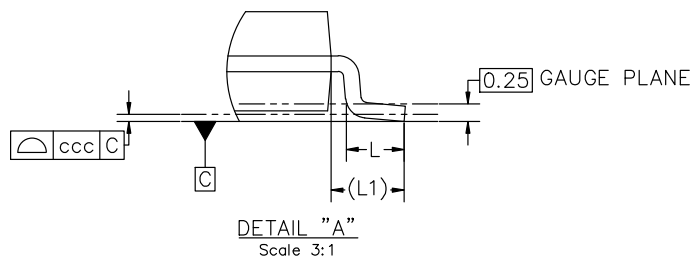
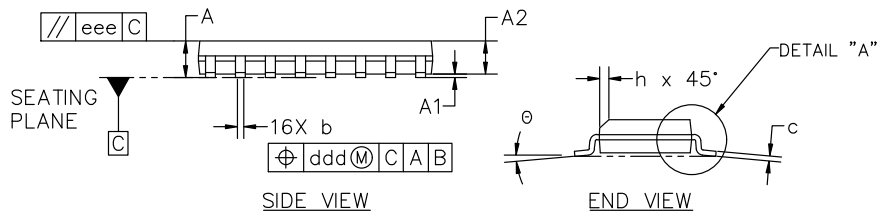
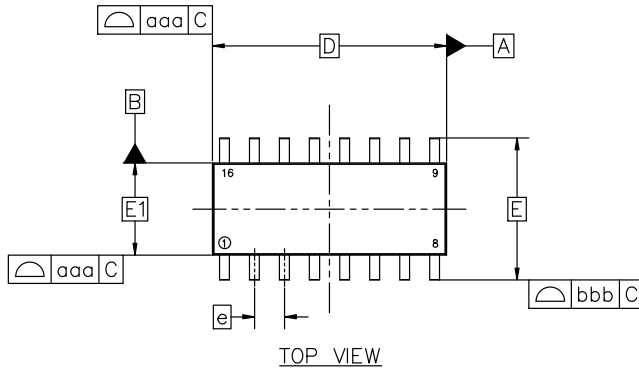



SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

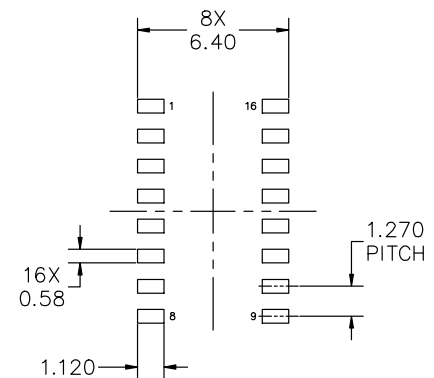
DATE 18 OCT 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
A2	1.25	1.37	1.50
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



*FOR ADDITIONAL INFORMATION ON OUR
PB-FREE STRATEGY AND SOLDERING DETAILS,
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AND MOUNTING TECHNIQUES REFERENCE
MANUAL, SOLDERM/D

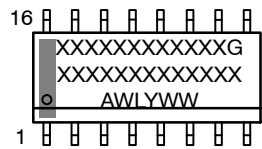
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SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

DATE 18 OCT 2024

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR	STYLE 2: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE	STYLE 3: PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4	STYLE 4: PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1
STYLE 5: PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE	STYLE 7: PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH	

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